



RoHS Compliant
Aug 2004



Compliant with the following conditions:

1. Leaded quantity of product below 100 ppm
2. Lead-free process

Soldering conditions

Shape	Symbol	Hand Soldering	DIP Soldering	Reflow Soldering
Lead Frame & Holder Type		<ol style="list-style-type: none"> 1. Temp. at tip of iron: 400°C Max. (30 W Max.) 2. Soldering time: 3 sec Max. 3. Distance: 3 mm Min. (from solder joint to case) 	<ol style="list-style-type: none"> 1. Preheat temp. : 100°C Max. 60 sec Max. 2. Bath temp.: 265°C Max. 3. Bath time: 5 sec Max. 4. Distance: 3 mm Min. (from solder joint to case) 	No
SMD Type		<ol style="list-style-type: none"> 1. Temp. at tip of iron: 350°C Max. (30 W Max.) 2. Soldering time: 3 sec Max. 	<ol style="list-style-type: none"> 1. Preheat temp. : 120 -150°C 60 - 120 sec 2. Bath temp.: 260°C Max. 3. Bath time: 5 sec 	<ol style="list-style-type: none"> 1. Preheat temp. : 150 -180°C 120 sec Max. 2. Operating temp.: Above 230°C, 40 sec Max. 3. Peak temp.: 260°C Max., 10 sec Max.